

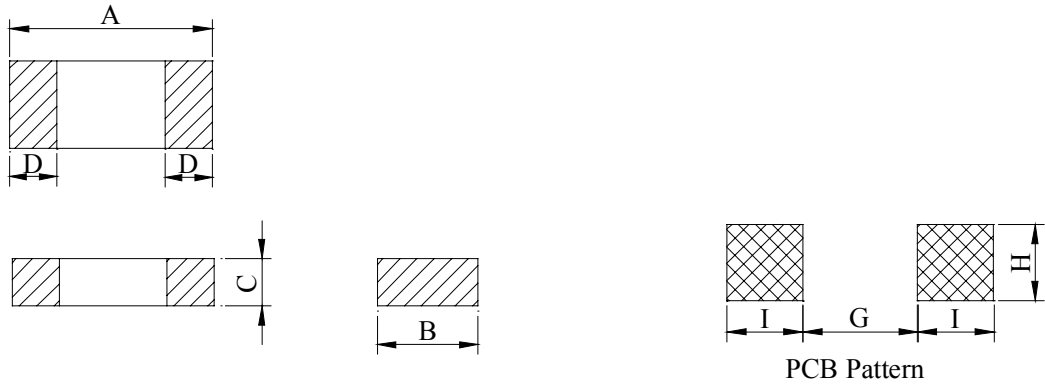
SPECIFICATION FOR APPROVAL

REF :

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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	MU2029□□□□5□
		ABC'S ITEM NO.	

. CONFIGURATION & DIMENSIONS :



Unit : m/m

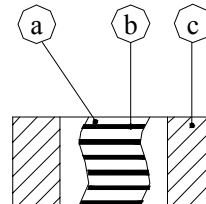
Series	A	B	C	D	G	H	I
MU2029	2.10±0.20	1.25±0.20	0.85±0.20	0.50±0.30	1.0	1.0	1.0

. SCHEMATIC DIAGRAM :



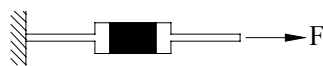
. MATERIALS :

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal electrode : Ag/Ni/Sn (Lead content 100ppm max.)
- d . Remark : Lead content 1000ppm max. include ferrite



. GENERAL SPECIFICATION :

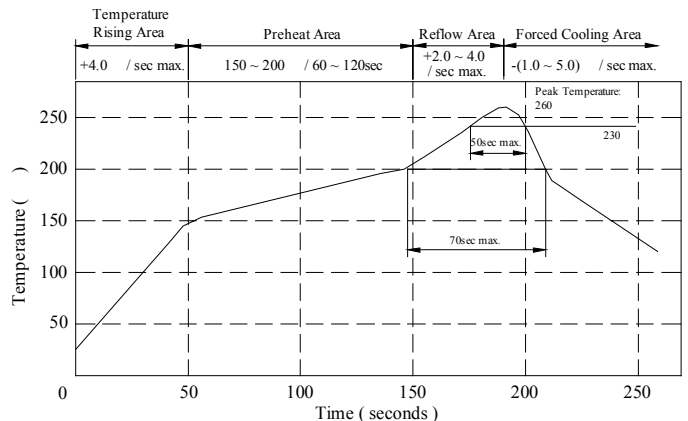
- a . Storage temp. : -40 ---- +105
- b . Operating temp. : -25 ---- +85
- c . Terminal Strength :



Type	F (kgf)	time (sec)
MU2029	0.6	30±5

- d . Solderability : Preheat : 150±25°C for 60 seconds
 Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent
 Solder temp. : 260±5
 Flux : Rosin
 Dip time : 4±1 seconds

Peak Temp : 260 max.
 Max time above 230 : 50sec max.
 Max time above 200 : 70sec max.



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. ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance (Ω)	Z Test Freq. (MHz)	RDC (Ω) max.	Ir (mA) max.
MU2029100Y5□	5 ~ 15	100	0.04	2200
MU2029170Y5□	17.0±25%	100	0.04	2000
MU2029300Y5□	30.0±25%	100	0.05	1500
MU2029470Y5□	47.0±25%	100	0.05	1500
MU2029700Y5□	70.0±25%	100	0.10	1000
MU2029121Y5□	120.0±25%	100	0.15	800
MU2029221Y5□	220.0±25%	100	0.20	600
MU2029301Y5□	300.0±25%	100	0.20	500
MU2029421Y5□	420.0±25%	100	0.25	500
MU2029601Y5□	600.0±25%	100	0.30	500
MU2029102Y5□	1000.0±25%	100	0.40	500

1). □ : Packaging Information... A } Bulk B } Taping Reel

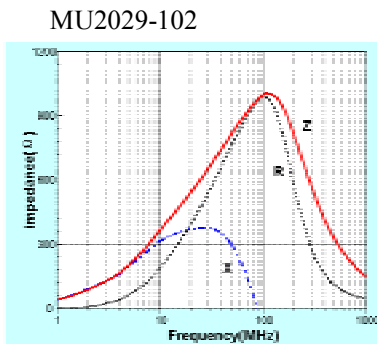
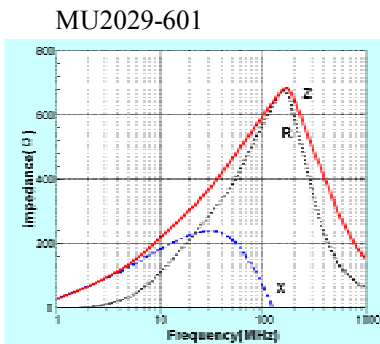
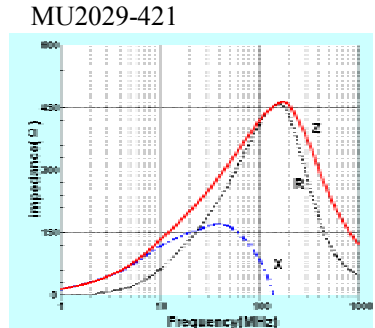
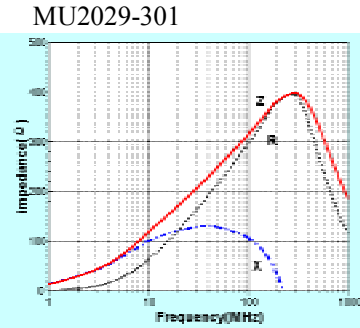
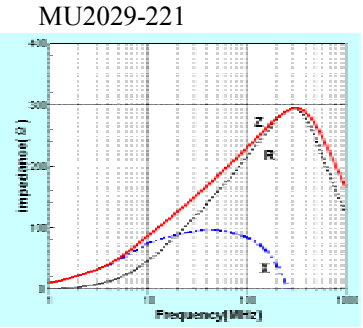
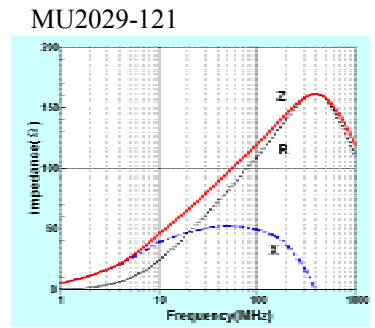
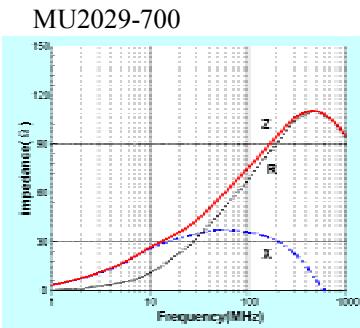
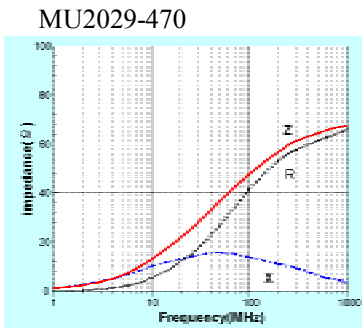
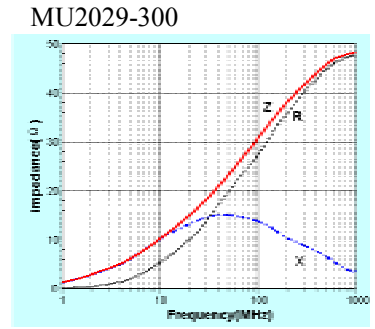
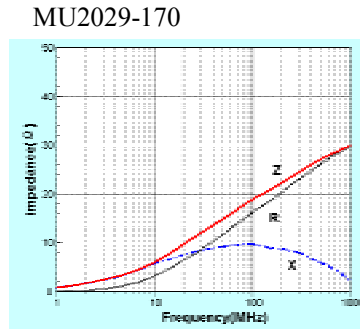
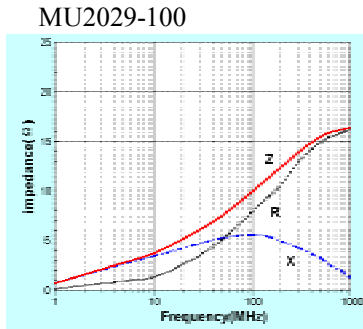
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. IMPEDANCE VS. FREQUENCY CHARACTERISTICS :



AE-001A

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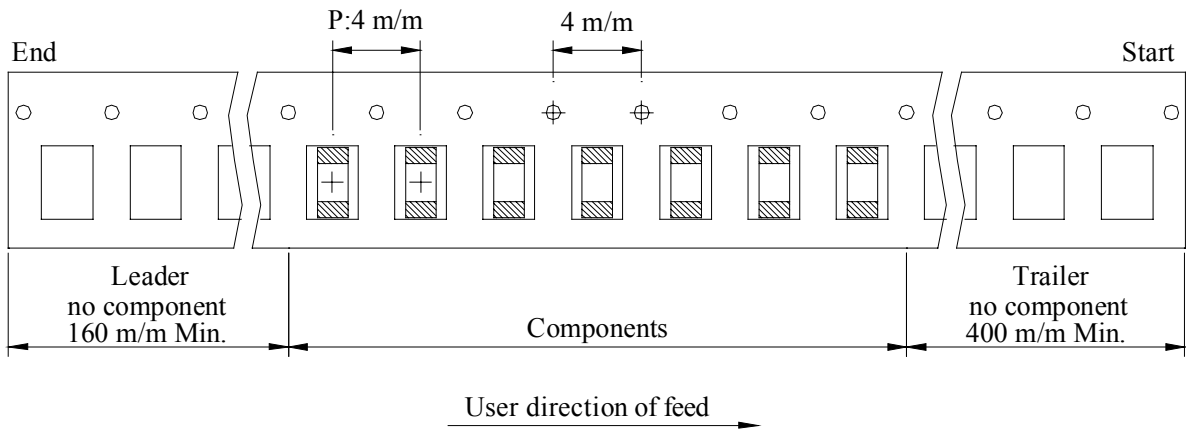
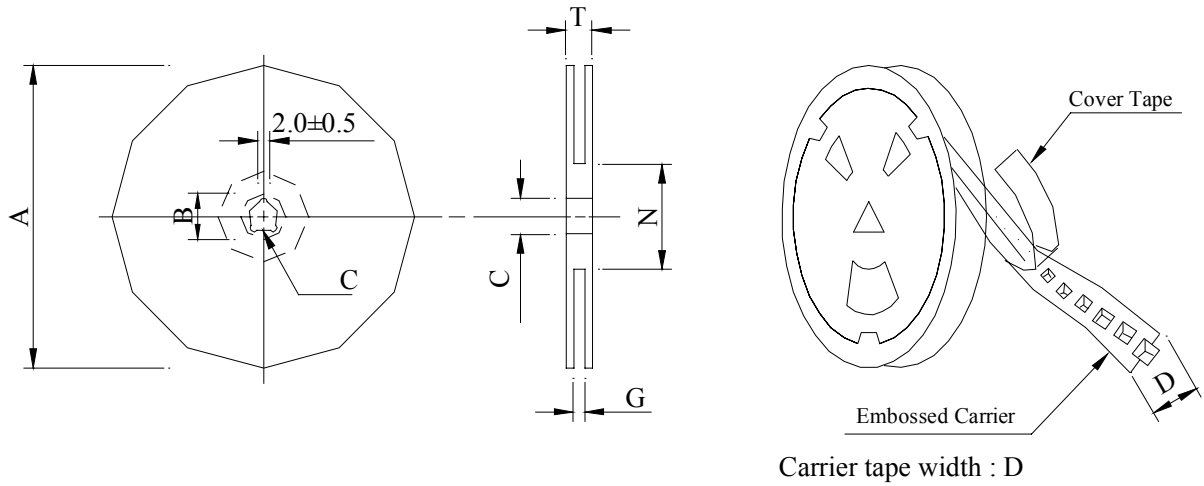
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PACKAGING INFORMATION

(1) Configuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY(pcs)	G.W. (Kg)	Size (cm)
MU2029	4,000	120	07 - 08	200,000	8.5	41 x 39 x 22

AE-001A



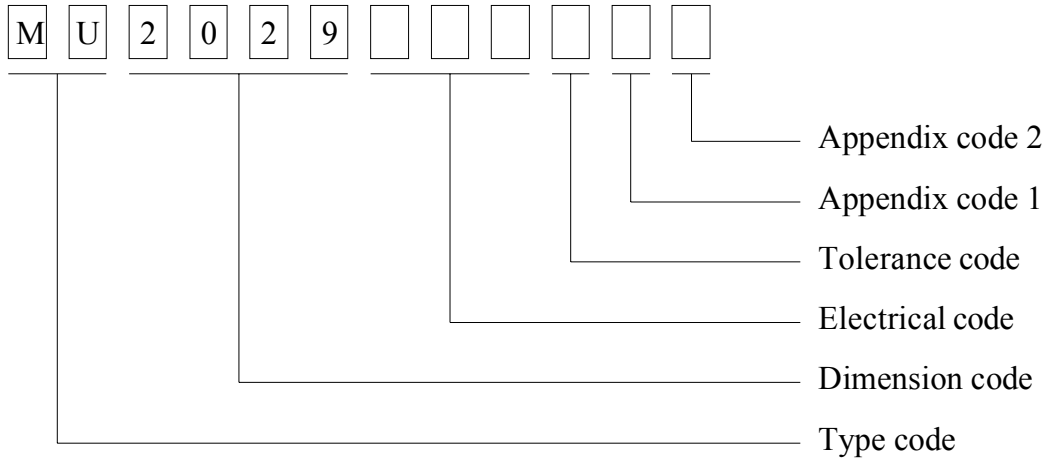
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. DWG EXPRESSION :



- Appendix code 1 : S : Standard products
 A K , M R , T Z : Special products
 L : Standard Lead Free products
 1 ~ 9 : Special Lead Free products

Appendix code 2 :

Code	Inner package	Inner package Q'TY	Remark
A	Empty	Empty	
B	T / R (Reel package)	4000 pcs	